



ELIC 5686779

#15/supl
W8/1b/00

1 THE UNITED STATES PATENT AND TRADEMARK OFFICE
2 Priority Application Serial No. 09/148,723
3 Priority Filing Date September 3, 1998
4 Inventor Warren M. Farnsworth et al.
5 Assignee Micron Technology, Inc.
6 Priority Group Art Unit 3729
7 Priority Examiner D. Tugbang
8 Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate
6 (see w/paper #13)

7 **RESPONSE TO MAY 22, 2000 OFFICE ACTION**

8 **PRELIMINARY AMENDMENT TO ACCOMPANY CPA FILING**

9 *Supl*

10 To: BOX CPA
11 From: Frederick M. Fliegel, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)
12 Assistant Commissioner for Patents
13 Washington, D.C. 20231
14 Wells, St. John, Roberts, Gregory & Matkin P.S.
15 601 W. First Avenue, Suite 1300
16 Spokane, WA 99201-3817

17 Sir:

18 Responsive to the Final Office Action dated May 22, 2000,
19 Applicant amends and remarks as follows [unless otherwise indicated,
20 deletions are bracketed, additions are underlined]:

21 **AMENDMENTS**

22
23 **In the Claims**